

IN THE CLAIMS

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1-12. (*Canceled*)

13. (*Currently Amended*) A method for megasonic cleaning of  
semiconductor wafers comprising the steps of:  
generating two or more parallel sets of megasonic waves in a cleaning  
fluid;  
5 immersing semiconductors in the cleaning fluid;  
moving the wafers in the cleaning fluid ~~along a path~~ through said  
megasonic waves and transverse to the megasonic waves ~~and traversing said~~  
~~path two or more times.~~

14. (*Original*) The method of claim 13 wherein the megasonic waves  
are generated across parallel regions of the fluid and the step of moving the  
wafers comprises reciprocating the wafers through said parallel regions.

15. (*Currently Amended*) A method for megasonic cleaning of  
semiconductor wafers comprising the steps of:  
generating megasonic waves with a laminar ~~energy wave front~~ flow in a  
cleaning fluid in a container; and

- 5            intercepting the generated waves inside the container and dispersing  
the waves in a divergent manner; and  
exposing the semiconductor wafers to the dispersed megasonic waves  
within the cleaning fluid.

16-26. (Canceled)